

## [The R&D program PRIIM launched by IPDiA reaches its end](#)

*Caen, March 18th 2014 Four years after the launch of its PRIIM project (platform for the realization of shared industrial innovation), IPDiA presents the major technological results achieved during this program.*

*Online PR News* â€“ 26-March-2014 â€“ In January 2010, IPDiA announced the launch of a major R&D program named PRIIM, in collaboration with industrial partners (Movea, Sorin, Gemalto and Kalray) and technological partners (CEA-Leti, CRISMAT(1), 3D Plus and CNRS LAAS). The aim of this program led by IPDiA and supported by Bpifrance was to define new application requirements for high-growth markets such as implantable medical devices (stimulators, defibrillators, motion detectors), multimedia chips and complex embedded systems.

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Within this project, IPDiA and CEA-Leti highlight three technological results related to high performance and size reduction benefits:

With 250 nF/mm at the beginning of the project, the capacitance density for 3D silicon capacitors has achieved a new world record with a value increased by a factor of 4.

The work conducted on components thickness originally at 250 m has been a success and a new range of ultra low profile capacitors with a thickness of 80 m has been introduced.

The innovations carried out on TSV (Through Silicon Via or interconnects through the silicon) have led to a significant increase in the electrical performance of micro-modules.

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On top of these R&D results, the other main objective of PRIIM was industrialization of these technologies. Thanks to the partnerships set up, several demonstrators have been developed and have reached the qualification stage with IPDiA's key customers. Many demonstrators refer to medical applications for which IPDiA integrated systems enable savings of up to 90 % of the total size of the product and increased electrical performance.

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Finally, PRIIM has confirmed the strong partnership between IPDiA and CEA-Leti and unveiled a new cooperation with CRISMAT. IPDiA has taken advantage of these 4 years R&D to sustain its international leadership as silicon component manufacturer and strengthen its position in the implantable medical devices market.

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About IPDiA:

IPDiA, leader in integration technologies for silicon passive components, proposes a global miniaturization

offer with a very high technological and economic performance level. The company focuses on the following main sectors: medical, lighting, communication, defense, aerospace, industrial and automotive. For further information, visit [www.ipdia.com](http://www.ipdia.com)

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